

**In the Claims**

Claim 1 (previously presented): A semiconductor package comprising a solder having an alpha flux of less than  $0.0005 \text{ cts/cm}^2/\text{hr}$ .

Claim 2 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Ag, Bi, Cu, In, Pb or Sn.

Claim 3 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Ag.

Claim 4 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Sn.

Claim 5 (original): The semiconductor package of claim 1 wherein the solder is substantially lead-free.

Claim 6 (original): The semiconductor package of claim 1 wherein the solder is lead-containing solder that is at least 99 weight% lead.

Claim 7 (previously presented): The semiconductor package of claim 1 wherein the solder predominately comprises Bi, Cu or In.

Claim 8 (previously presented): The semiconductor package of claim 1 wherein the solder has an alpha flux of less than  $0.0002 \text{ cts/cm}^2/\text{hr}$ .

Claim 9 (previously presented): The semiconductor package of claim 1 wherein the solder has an alpha flux of less than  $0.0001 \text{ cts/cm}^2/\text{hr}$ .

Claims 10-29 (canceled).